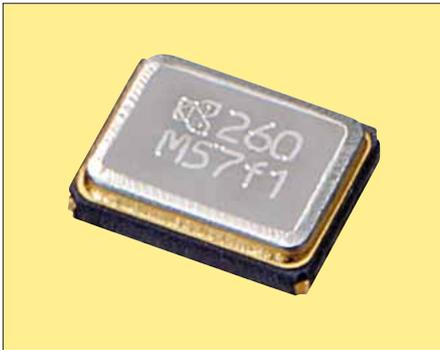


3.2×2.5mm



Pb Free

RoHS Conforming

**Features**

- Reference frequency for telecommunication systems
- Reflow compatible
- Using Ceramic Package resulting in high reliability
- Small and low profile

**Applications**

- Cellular phone, IC Card, GPS

**How to Order**

KSX-23-26000K C A-Q C 0 R  
① ② ③ ④ ⑤ ⑥ ⑦ ⑧

- ① Type
- ② Nominal Frequency

Code	Freq.(kHz)	Code	Freq.(kHz)
19200K	19200.000	32000K	32000.000
19680K	19680.000	38400K	38400.000
19800K	19800.000	40000K	40000.000
26000K	26000.000		

\* Please inquire about frequencies other than the above.

- ③ Load Capacitance

C	12pF
---	------

- ④ Frequency Stability

A	±10ppm
---	--------

- ⑤ Operating Temperature

Q	-30°C to +85°C
---	----------------

- ⑥ Frequency Temperature Stability

C	±15ppm
---	--------

- ⑦ Frequency Offset

0	0Hz(Standard)
---	---------------

- ⑧ Packaging

R	Taping
---	--------

**Specifications**

Items	Symbol	Specification	Units	Remarks
Frequency Range	F <sub>o</sub>	19200~40000	kHz	
Overtone Order	—	Fundamental	—	
Frequency Tolerance	ΔF/F	±10	ppm	@ 25°C
Frequency Temperature Character	ΔF/T	±15	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	Cl	Table 1	ohm	
Level of Drive	—	Table 2	μW	
Load Capacitance	C <sub>L</sub>	12	pF	
Operating Temp. Range	T <sub>OPR</sub>	-30~+85	°C	
Storage Temp. Range	T <sub>STG</sub>	-40~+85	°C	

\* Taping packing : one unit 1,000pcs & 3,000pcs  
\* Please inquire about specifications other than the above.

**Table1 Motional Series Resistances**

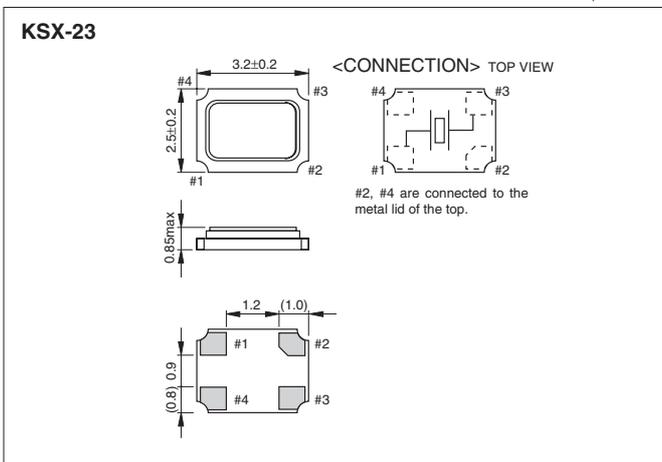
Frequency Range	Motional Series Resistance	Units
19200~24999kHz	60Max	ohm
25000~40000kHz	40Max	

**Table2 Level of Drive**

Frequency Range	Level of Drive	Units
19200~40000kHz	10(Max 100)	μW

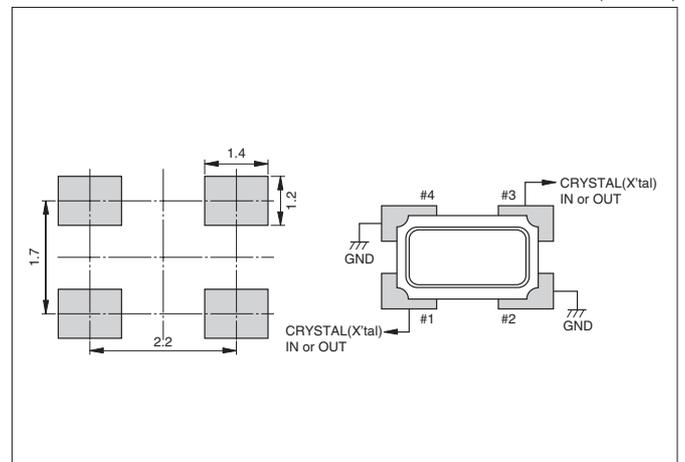
**Dimensions**

(Unit : mm)



**Recommended Land Pattern**

(Unit : mm)



5.0×3.2mm



Pb Free

RoHS Comforming

**Features**

- Reference frequency for telecommunication systems
- Reflow compatible
- Using Ceramic Package resulting in high reliability
- Small, low profile and market standard dimensions

**Applications**

- Cellular phone, IC Card, GPS
- Remote keyless entry

**How to Order**

KSX-35-13000K C A-Q C 0 R  
① ② ③ ④ ⑤ ⑥ ⑦ ⑧

①Type

②Nominal Frequency

Code	Freq.(kHz)	Code	Freq.(kHz)
13000K	13000.000	19440K	19440.000
13560K	13560.000	19680K	19680.000
14400K	14400.000	19800K	19800.000
16800K	16800.000	26000K	26000.000
19200K	19200.000		

\* Please inquire about frequencies other than the above.

③Load Capacitance

C	12pF
---	------

④Frequency Stability

A	±10ppm
---	--------

⑤Operating Temperature

Q	-30°C to +85°C
---	----------------

⑥Frequency Temperature Stability

C	±15ppm
---	--------

⑦Frequency Offset

0	0Hz(Standard)
---	---------------

⑧Packaging

R	Taping
---	--------

**Specifications**

Items	Symbol	Specification	Units	Remarks
Frequency Range	Fo	12600~27820	kHz	
Overtone Order	—	Fundamental	—	
Frequency Tolerance	ΔF/F	±10	ppm	@ 25°C
Frequency Temperature Character	ΔF/T	±15	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	Cl	Table 1	ohm	
Level of Drive	—	Table 2	μW	
Load Capacitance	CL	12	pF	
Operating Temp. Range	T <sub>OPR</sub>	-30~+85	°C	
Storage Temp. Range	T <sub>STG</sub>	-40~+85	°C	

\* Taping packing : one unit 1,000pcs & 3,000pcs  
\* Please inquire about specifications other than the above.

**Table1 Motional Series Resistances**

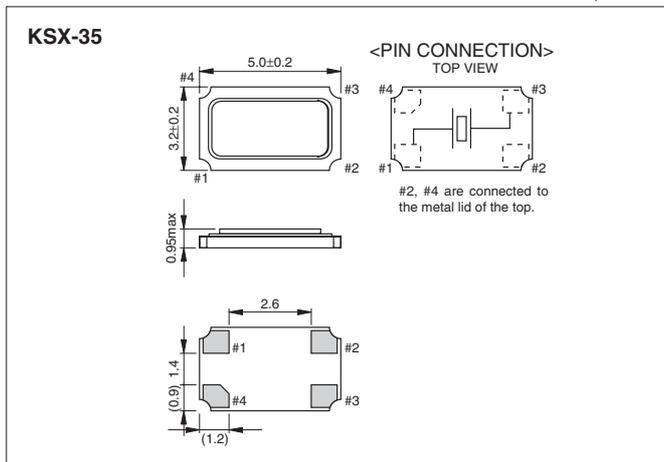
Frequency Range	Motional Series Resistance	Units
12600~18999kHz	60Max	ohm
11000~25999kHz	50Max	
26000~27820kHz	40Max	

**Table2 Level of Drive**

Frequency Range	Level of Drive	Units
12600~27820kHz	10(Max 100)	μW

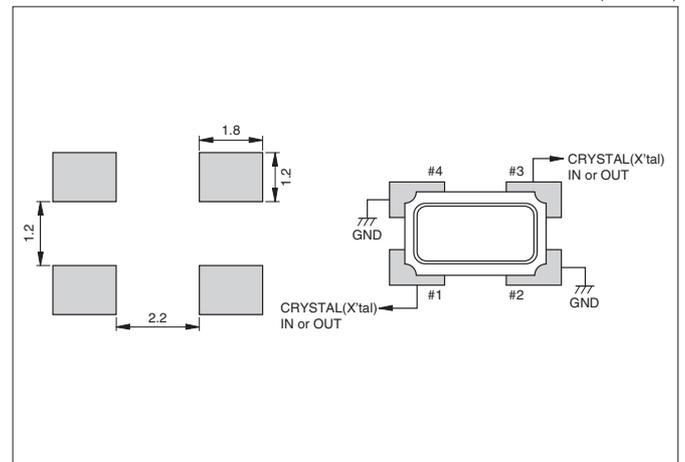
**Dimensions**

(Unit : mm)



**Recommended Land Pattern**

(Unit : mm)



6.0×3.5mm



Pb Free

RoHS Conforming

**Features**

- Reference frequency for telecommunication systems
- Reflow compatible
- Using Ceramic Package resulting in high reliability
- Small, low profile and market standard dimensions

**Applications**

- Cellular phone, IC Card, GPS
- Remote keyless entry

**How to Order**

KSX-36-13000K C A-Q C 0 R  
① ② ③ ④ ⑤ ⑥ ⑦ ⑧

- ① Type
- ② Nominal Frequency

Code	Freq.(kHz)	Code	Freq.(kHz)
09843K	9843.750	19200K	19200.000
13000K	13000.000	19440K	19440.000
13560K	13560.000	19680K	19680.000
13568K	13568.750	19800K	19800.000
14400K	14400.000	26000K	26000.000
16800K	16800.000	27820K	27820.800

\* Please inquire about frequencies other than the above.

- ③ Load Capacitance

C	12pF
---	------

- ④ Frequency Stability

A	±10ppm
---	--------

- ⑤ Operating Temperature

Q	-30°C to +85°C
---	----------------

- ⑥ Frequency Temperature Stability

C	±15ppm
---	--------

- ⑦ Frequency Offset

0	0Hz(Standard)
---	---------------

R	Taping
---	--------

**Specifications**

Items	Symbol	Specification	Units	Remarks
Frequency Range	F <sub>o</sub>	9843~27820	kHz	
Overtone Order	—	Fundamental	—	
Frequency Tolerance	ΔF/F	±10	ppm	@ 25°C
Frequency Temperature Character	ΔF/T	±15	ppm	ref@ 25°C Over Operating Temp Range
Motional Series Resistance	Cl	Table 1	ohm	
Level of Drive	—	Table 2	μW	
Load Capacitance	C <sub>L</sub>	12	pF	
Operating Temp. Range	T <sub>OPR</sub>	-30~+85	°C	
Storage Temp. Range	T <sub>STG</sub>	-40~+85	°C	

\* Taping packing : one unit 1,000pcs & 3,000pcs  
\* Please inquire about specifications other than the above.

**Table1 Motional Series Resistances**

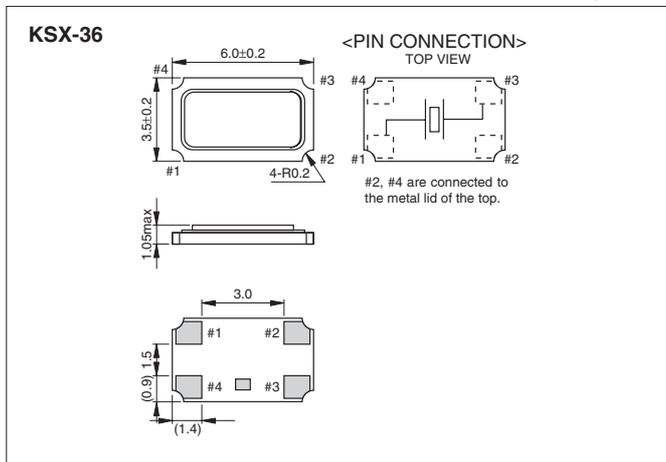
Frequency Range	Motional Series Resistance	Units
9843~11999kHz	60Max	ohm
12000~25999kHz	40Max	
26000~27820kHz	30Max	

**Table2 Level of Drive**

Frequency Range	Level of Drive	Units
9843~27820kHz	10(Max 100)	μW

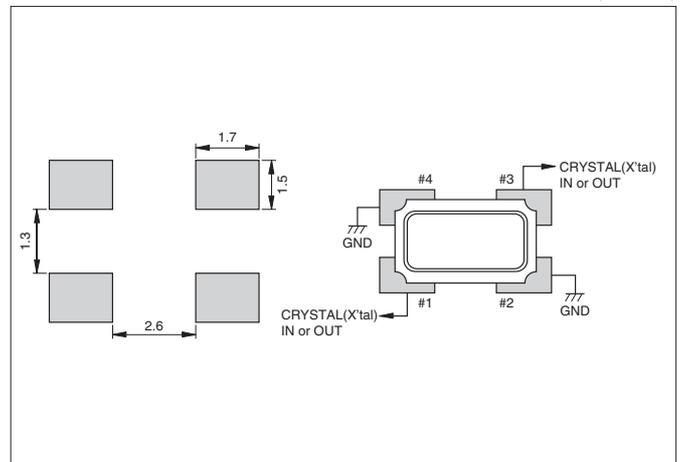
**Dimensions**

(Unit : mm)



**Recommended Land Pattern**

(Unit : mm)



## 1. Shock & Drop • Vibration

Do not inflict excessive shock and mechanical vibration that exceeds the norm, such as hitting or mistakenly dropping, when transporting and mounting on a board. There are cases when pieces of crystal break, and pieces that are used become damaged, and become inoperable. When a shock or vibration that exceeds the norm has been inflicted, make sure to check the characteristics.

## 2. Cleaning

Since a crystal piece can be broken by resonance when a crystal device is cleaned by ultrasonic cleaning. Be careful when carrying out ultrasonic cleaning.

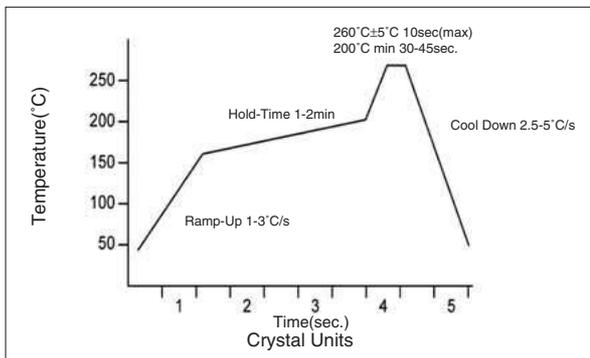
## 3. Soldering conditions

To maintain the product reliability, please follow recommended conditions.

### Standard soldering iron conditions

	Crystal Units
Soldering iron	280°C ~ 340°C
Time	3+1/-0sec. max

### Reflow conditions (Example)



Recommended reflow Conditions vary depending upon products. Please check with the respective specification for details.

## 4. Mounting Precautions

### Leaded Devices

The special glass, located where the lead of the retainer base comes out, is aligned with the coefficient of thermal expansion of the lead, If the glass is damaged and cracks appear, there may be cases in which performance deteriorates and it fails to operate.

Consequently, when making the device adhere closely and applying solder, align the gap of the hole of the board with the gap of the lead and insert without excessive force.

When making the device adhere closely to a through hole board and applying solder, be careful that the solder does not get into the metal part of the retainer base and cause a short. Putting in an insulation spacer is one more method of preventing a short circuit.

When the lead is mounted floating, fix it as far as possible so that contact with other parts and the breakage due to the fatigue, and the mechanical resonance of the lead will not occur.

When the lead is bent and used, do not bend the lead directly from the base, separate it 0.5mm or more and then bend it. When bending, before attaching to the board, fix the place where the lead comes out in advance and attach it after bending so that a crack does not occur in the glass part.

### Surface Mount Devices

The lead of the device and the pattern of the board is soldered on the surface. Since extreme deformation of the board tears off the pattern, tears off the lead metal, cracks the solder and damages the sealed part of the device and there are cases in which performance deteriorates and operation fails, use it within the stipulated bending conditions. Due to the small cracks in the board resulting from mounting, please pay sufficient attention when attaching a device at the position where the warping of the board is great.

When using an automatic loading machine, as far as possible, select a type that has a small impact and use it while confirming that there is no damage.

Surface mount devices are NOT flow soldering compatible.

## 5. Storage Condition

Since the long hour high temperature and low temperature storage, as well as the storage at high humidity are causes of deterioration in frequency accuracy and solderability.

Parts should be stored in temperature range of -5 to +40°C, humidity 40 to 60% RH, and avoid direct sunlight. Then use within 6 months.

## For Proper Use of Crystal Units

### 1. Characteristics of crystal units

The thickness of crystal vibrator of the AT cut crystal unit as described in the previous page differs depending on the overtone mode.

#### (1) Relationship between thickness of crystal blank and oscillation frequency

Cut angle/mode overtone	Frequency range (MHz)	Formula of thickness of crystal blank
AT/Fundamental mode	3.5~33	$1.67/f$
AT/3 <sup>rd</sup> O. T	33~100	$5.01/f$
AT/5 <sup>th</sup> O. T	100~150	$8.35/f$
AT/7 <sup>th</sup> O. T	150~200	$11.69/f$

f : Series resonance frequency. (MHz)

In case of calculating the thickness of AT-cut 16MHz  
 $t=1.67/16=0.104(\text{mm})$

#### (2) Examples of specifications for frequency-temperature characteristics

The frequency-temperature characteristics of the AT cut crystal unit are tertiary curves.

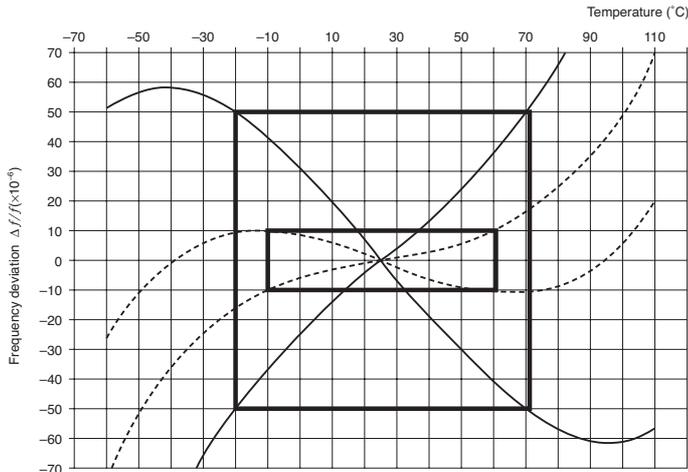
The diagram below shows examples of the tertiary curves that pass temperature range and frequency deviation specifications.

The range enclosed by the smaller rectangular satisfies the following specification:

$$\pm 10 \times 10^{-6} \text{ (-10 to 60: } 25^\circ\text{C)}$$

The range enclosed by the larger rectangular satisfies the following specification:

$$\pm 50 \times 10^{-6} \text{ (-20 to 70: } 25^\circ\text{C)}$$



\* These are examples. Required frequency-temperature specifications are determined through individual consultations.

#### (3) Equivalent electric circuit and equivalent constant of crystal unit

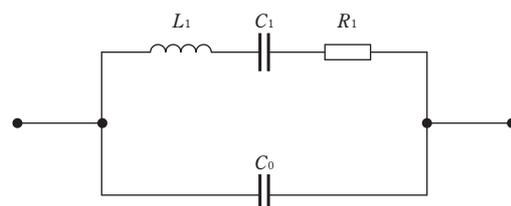
The following equivalent constants are used near the resonance frequency.

$L_1$  : Motional inductance in the equivalent electric circuit

$C_1$  : Motional capacitance in the equivalent electric circuit

$R$  : Motional resistance in the equivalent electric circuit

$C_0$  : Parallel capacitance in the equivalent electric circuit



Equivalent electric circuit of a quartz crystal unit

**(4) Items calculated by equivalent constants and load capacitance**

$f_s$ : Series resonance frequency  $f_s = \frac{1}{2\pi\sqrt{L_1 \cdot C_1}}$

$f_p$ : Parallel resonance frequency  $f_p = \frac{1}{2\pi\sqrt{L_1 \frac{C_0 \cdot C_1}{C_0 + C_1}}}$

$g$ : Capacitance ratio  $\gamma = \frac{C_0}{C_1}$

$f_L$ : Load resonance frequency  $f_L = f_s \left( \frac{C_1}{2 \cdot (C_0 + C_L)} + 1 \right)$

$R_L$ : Load resistance  $R_L = R_1 \left( 1 + \frac{C_0}{C_L} \right)^2$

$C_L$ : Load capacitance  $C_L = \frac{C_1}{2} \cdot \frac{1}{(f_L/f_s) - 1} - C_0$

$Q$ : Quality factor  $Q = \frac{2\pi \cdot f_s \cdot L_1}{R_1} = \frac{1}{2\pi \cdot f_s \cdot C_1 \cdot R_1}$

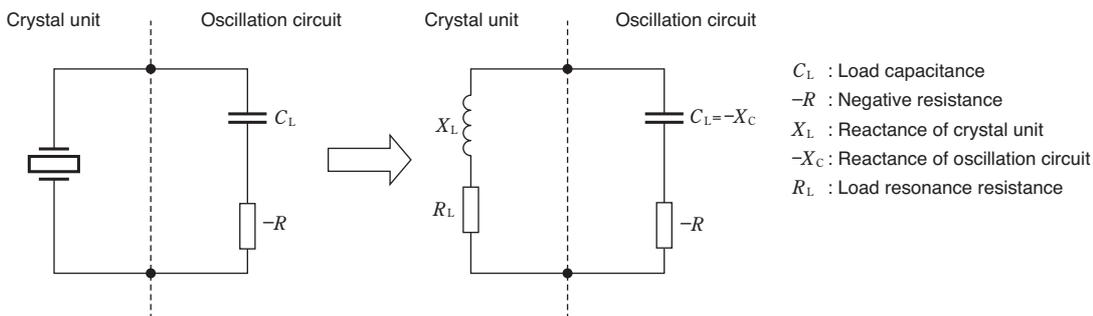
The equation  $f_L$  shows that  $f_L$  varies as load capacitance  $C_L$  connected to the crystal unit changes and that  $f_L$  becomes larger, as  $C_L$  becomes smaller.

The equation  $R_L$  shows the change in impedance with a load capacitance connected. The impedance of crystal unit becomes larger as  $C_L$  becomes smaller.

**2. Oscillation circuit and crystal unit**

**(1) Equivalent circuit of oscillation circuit and oscillation conditions**

A simplified equivalent circuit is shown below.



The oscillation start-up conditions are described as

$$R_L \geq |-R|$$

, and in order to oscillate the crystal unit accurately, it must be designed such that the negative resistance of the oscillation circuit becomes bigger comparing with the resonance resistance value at the time of loading. This ratio is called oscillation margin degree  $M_{OSC}$  and it is one of critical factors when designing the oscillation circuit and is described as below.

For oscillation circuit designing conditions, it is recommended that an oscillation circuit be designed using a negative resistance of a value five to ten times or more larger than  $R_L$  calculated from the resonance resistance specification value.

$$M_{OSC} = |-R| / R_L \geq 5$$

In a steady oscillation state, the load resonance resistance is given as follows:

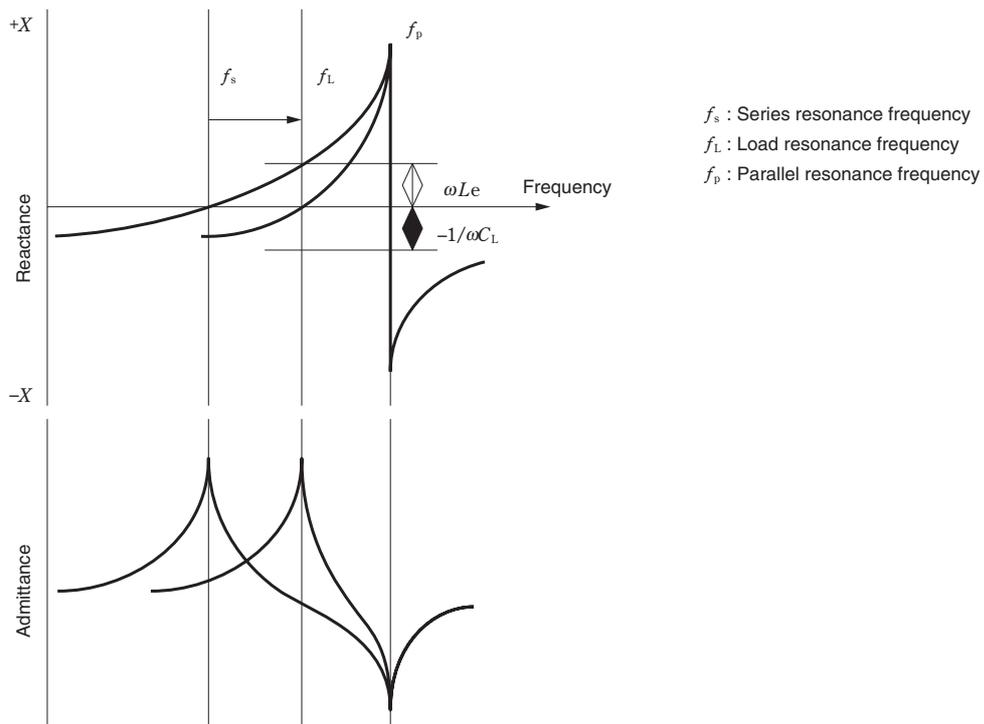
$$R_L = |-R|$$

The mutual conductance of the oscillation circuit decreases after the oscillation has started to continuously compensate for the power loss due to the load resonance resistance of the crystal unit, which continues oscillation.

The frequency condition is given as follows:

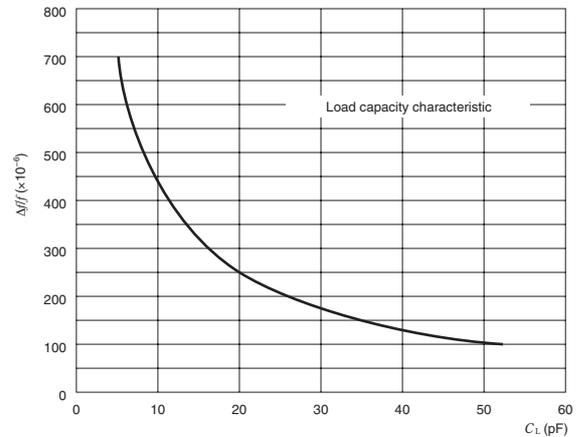
$$X_L = X_C, X_L - X_C = 0$$

As shown in the following figure, the reactance of the crystal unit varies to a value matching the load capacitance of the oscillation circuit  $C_L = X_C$ . Thus an oscillation frequency is determined.



**(2) Changes of load capacitance and oscillation frequency**

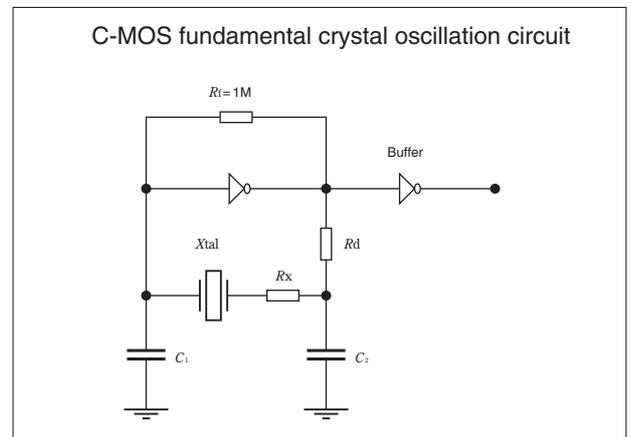
As shown above, the series resonance frequency of the crystal unit changes with load capacitance  $C_L$  of the oscillation circuit. In the actual oscillation circuit, however, fine adjustments of oscillation frequencies are carried out by varying  $C_L$  by the trimmer capacitor or the like. The following figure shows an example of load capacitance characteristics. The slope of the characteristics varies depending on the frequency, shape, the number of overtone mode, etc.



**3. Crystal oscillation circuit**

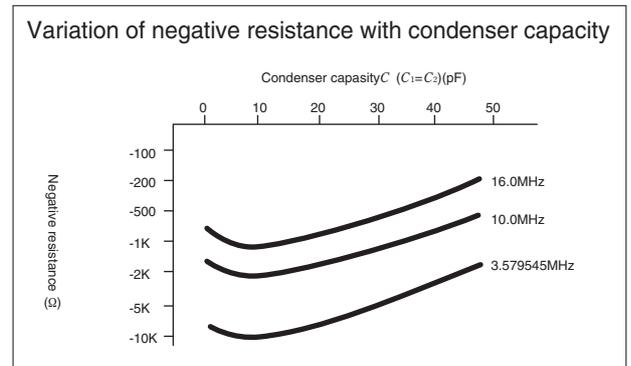
**(1) C-MOS fundamental crystal oscillation circuit**

As shown above, the series resonance frequency of the crystal The figure on the right shows a standard C-MOS inverter crystal oscillation circuit for oscillating crystal unit with fundamental mode. \*  $R_x$  is an element to reduce excitation current of the crystal unit preventing frequency fluctuation, but  $R_x$  is not used in some cases.

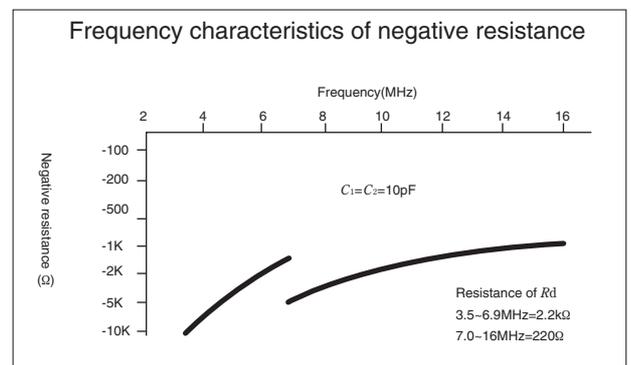


Characteristics of the circuit when load capacitances  $C_1$  and  $C_2$  are changed under the condition of  $C_1 = C_2$  are shown in the figure on the right.

It is not desirable that the excessive increase of the value of condenser leads to a decrease of the negative resistance resulting in increasing the possibility of oscillation failure.



$R_d$  mainly adjusts frequency characteristics of the negative resistance and is used to prevent oscillating by third Overtone mode. In case of a bigger circuit of the negative resistance, there is a case it is used to prevent the abnormal oscillation.



Selection of ICs and circuit constants by frequency bands

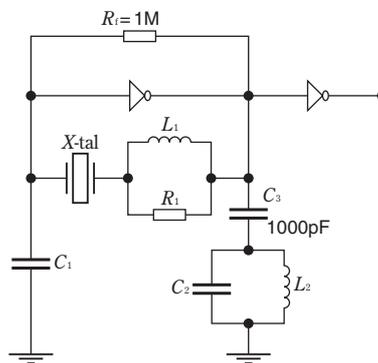
Frequency	3~4.9(MHz)	5~6.9(MHz)	7~9.9(MHz)	10~19.9(MHz)	20~30(MHz)
IC	TC4069UB TC4SU69F			TC74HCU04A TC7SU04F TC7WU04FU	TC74VHCU04 TC7SHU04F TC7WHU04FU
$R_f$	1M				
$R_d$ *1	1500( )	470( )	0( )	0( )	0( )
$R_x$ *2	0~1500				
$C_1, C_2$ *3	6~22(pF)			6~15(pF)	6~15(pF)

\*1: Necessary for preventing overtone oscillation and must be changed depending on the frequency band or the  $C_1$  and  $C_2$  values.  
 \*2: Used to reduce excitation current of the crystal unit. Necessary for stable operation of small-sized crystal units.  
 \*3: The optimum value differs with the values of load capacitance and  $R_d$ .

**(2) C-MOS overtone crystal oscillation circuit**

This figure shows a standard C-MOS inverter crystal oscillation circuit to oscillate a crystal unit using the overtone mode.

C-MOS overtone crystal oscillation circuit



There are same cases when  $L_1$  and  $R_1$  are matched to the value of load capacitance.

**(3) Selection of ICs and circuit constants by frequency bands**

Frequency range	20~60(MHz)
IC	TC74VHCU04 TC7SHU04F TC7WHU04FU
$C_1$	3~10pF
$C_2$	10~22pF

**(4) Method of selecting circuit constants and functions of elements**

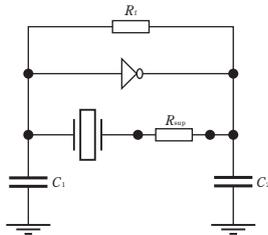
- $C_1$  : Forms load capacitance of the circuit together with  $C_2$ ,  $L_1$  and  $L_2$ . A value of approx. 5pF is used.
- $C_2$  : Forms load capacitance of the circuit together with  $C_1$ ,  $L_1$  and  $L_2$ . Prevents fundamental wave oscillation. Shall be selected so that  $C_2$  comes between the third overtone frequency at which resonance frequency with  $L_2$  is to make oscillation and 1/3 of the third overtone frequency. A value of 10 to 22pF is used.
- $C_3$  : A bypath capacitor
- $L_1$  : A coil to adjust load capacitance of the oscillation circuit to a value near the series. A value of several  $\mu$ H is used.
- $L_2$  : Forms load capacitance of the circuit together with  $C_1$ ,  $C_2$  and  $L_1$ . Prevents fundamental wave oscillation. Shall be selected so that  $L_2$  comes between the third overtone frequency at which resonance frequency with  $C_2$  is to make oscillation and 1/3 of the third overtone frequency. A value of 10 to 22pF is used.
- $R_1$  : A Q dump resistor for  $L_1$  . As an element for preventing self-excited oscillation, A value of several  $k\Omega$  to several tens of  $k\Omega$  is used.

\*  $L_1$  and  $R_1$  might not be used.

**(5) Method of checking oscillation circuit**

Some ICs have a low upper-limit value of usable frequency, so refer to individual IC catalog to make sure that the IC can oscillate a crystal unit with an adequate negative resistance.

The following figure shows an example of a C-MOS oscillation circuit. Check resistance  $R_{sup}$  is connected in series with the crystal unit to check the negative resistance. Use 3 to 22pF for  $C_1$  and  $C_2$ , and see the table below for values of check resistance.



Frequency range	Values of check resistance
3.5~4.5MHz	1.5k
4.6~6.0MHz	1.0k
6.1~10.0MHz	800
10.1~14.0MHz	500
14.1~20.0MHz	400

Using a spectrum analyzer or oscilloscope, check that every oscillation is normally activated while turning the power on and off several times. For oscillation circuits with no power regulator ICs, carefully check changes in the negative resistance against supply voltage and in frequencies.

When oscillation is normal, remove the check resistance before using the crystal circuit.

If oscillation is unstable or is not generated, gradually decrease the values of  $C_1$  and  $C_2$  until normal oscillation is obtained.

If normal oscillation cannot be generated near 10MHz or near 20MHz, replace the IC with a new one suitable for higher frequencies.

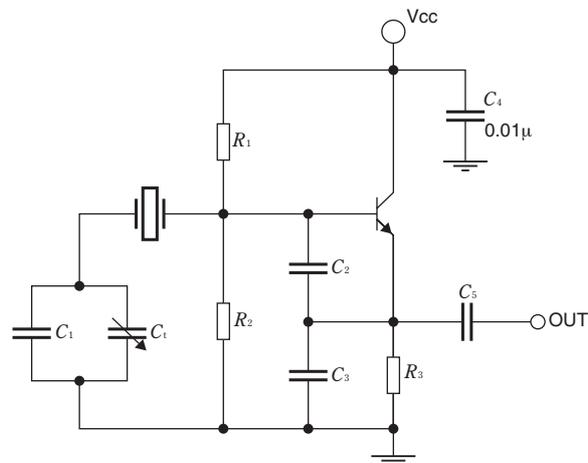
**(6) Load capacitance and oscillation frequency of transistor/fundamental crystal oscillation circuit**

Viewed from the connection terminals of a crystal unit, the load capacitance  $C_L$  of an oscillation circuit is generally comprised of  $C_1$ ,  $C_2$ , and  $C_3$  if stray capacitance of the circuit and the capacitance between base and emitter of the transistor are ignored. Since trimmer capacitor is adjusted to  $C_T = \text{MIN. to MAX.}$  for zero adjustment of the oscillation frequency, the value of  $C_L$  at this time can be obtained from the following equation.

$$C_{L\text{MIN.}} = \left( \frac{1}{C_1 + C_T} + \frac{1}{C_2} + \frac{1}{C_3} \right)^{-1} \sim C_{L\text{MAX.}} = \left( \frac{1}{C_1 + C_T} + \frac{1}{C_2} + \frac{1}{C_3} \right)^{-1}$$

When these calculation results are substituted for the following equation for load resonance frequency, the oscillation frequency can be obtained.

$$f_L = f_s \left( \frac{C_1}{2 \cdot (C_0 + C_L)} + 1 \right)$$



Select each circuit constant so that the adjustment ranges of upper and lower frequencies of this circuit are even on the basis of the frequency of a single crystal unit measured using a specified load capacity, and that the margin of  $\pm 8$  to  $10 \times 10^{-6}$  of the room temperature deviation of the crystal unit can be reserved.

To prevent the decrease in the negative resistance, always connect the crystal unit to the base of the transistor. For transistors used for oscillation circuits,  $h_{fe}$  and  $f_T$  are important.

To obtain the large negative resistance with small current consumption, select a transistor for high frequency amplification with  $h_{fe}$  of over 250 and  $f_T$  of 1GHz or more.

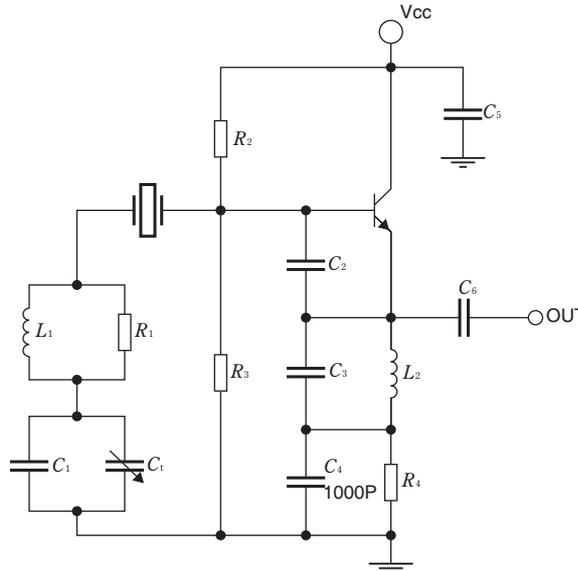
## (7) Transistor third overtone oscillation circuit

□ The resonance circuit comprised of  $L_2$  and  $C_3$  is required on the emitter side for preventing fundamental mode crystal oscillation. Set the resonance frequency to a value higher than the intermediate between fundamental wave frequency and third overtone frequency.

◻ Use  $L_1$ , referred to as an elongation coil, to connect the load capacitance of the oscillation circuit in series.  $R_1$  prevents self-excited oscillation by  $L_1$ . Since it is difficult in general to design the oscillation circuit having adequate negative resistance in the overtone oscillation frequency band, there are no other effective means of obtaining adequate oscillation margin except for preventing the increase of load resonance resistance  $R_L$  of the crystal unit.

$R_L$  in the equation of load resonance resistance can be made equal to  $R_S$  by connecting  $C_L$  in series, or making it infinite, which prevents increase in the load resonance resistance.

$$R_L = R_1 \left( 1 + \frac{C_0}{C_L} \right)^2$$



To prevent decrease in the negative resistance, connect the crystal unit to the base of the transistor as in the fundamental mode crystal oscillation circuit. To use the crystal circuit for both oscillation and multiplication, connect a parallel resonance circuit having multiplication frequency as resonance frequency to the collector of the transistor.

When selecting circuit constants for zero adjustment range by trimmer capacitor, set the constants to values obtained by adding approx.  $\pm 12$  to  $15 \times 10^{-6}$  to the room temperature deviation of the crystal unit, centering the value obtained by measuring the crystal unit with load capacitances in series. (When the room temperature deviation specification of the crystal unit is  $\pm 10 \times 10^{-6}$ )

**(8) Excitation power of oscillation circuit**

Normal operation of crystal units is not assured when excitation power is raised. The allowable excitation power varies depending on the shape of the crystal unit or the stability of targeted frequency. When highly accurate oscillation is required, however, it is recommended to use an oscillation circuit with an excitation power of 5 to 50  $\mu\text{W}$  or less. For other cases, refer to individual relevant crystal units on the pages of the catalog.

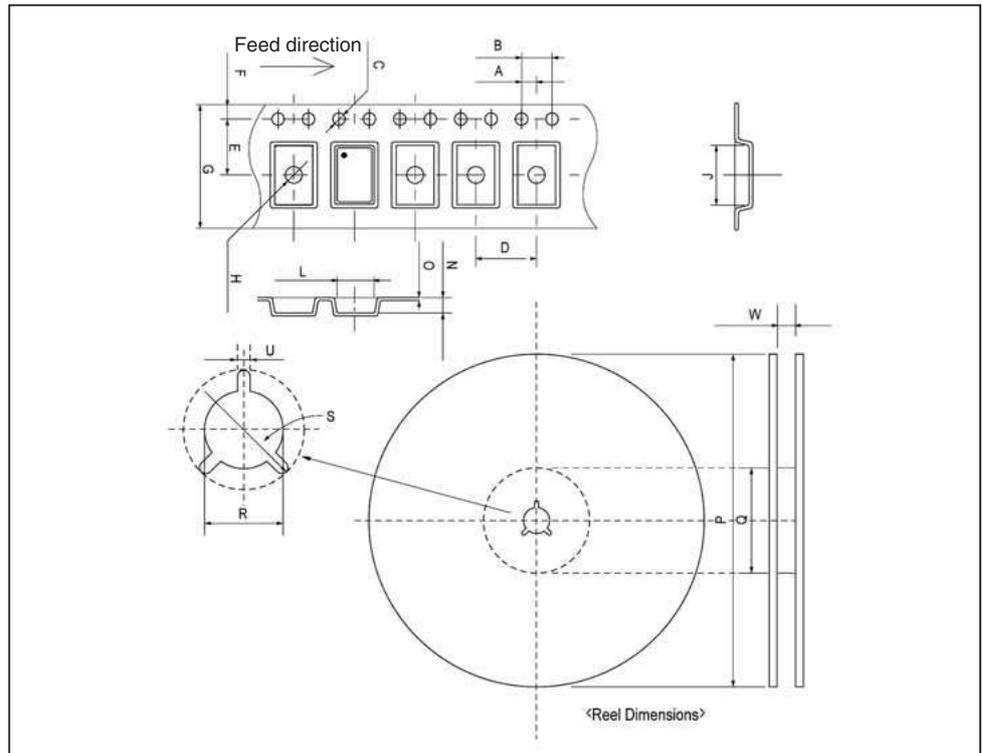
**(9) Precautions for designing printed circuit board**

Be sure to design printed circuit board patterns that connect a crystal unit with other oscillation elements so that the lengths of such patterns become shortest possible to prevent deterioration of characteristics due to stray capacitances and wiring inductance. For multi-layer circuit boards, it is important not to wire the ground and other signal patterns right beneath the oscillation circuit.

## Tape & Reel Specifications

### Crystal Units

	CX-2520SB	CX-3225SB (CX-101F)	
T A P E	A	2.0±0.05	2.0±0.05
	B	4.0±0.1	4.0±0.1
	C	φ1.55±0.05	φ1.55±0.05
	D	4.0±0.05	4.0±0.05
	E	3.5±0.05	3.5±0.05
	F	1.75±0.1	1.75±0.1
	G	8.0±0.2	8.0±0.2
	H	φ1.05±0.1	φ1.05±0.1
	J	3.5±0.1	3.5±0.1
	L	2.8±0.1	2.8±0.1
	N	0.85±0.1	0.85±0.1
O	0.25±0.05	0.25±0.05	
R E E L	P	φ180+0/-3	φ180+0/-3
	Q	φ60+1/-0	φ60+1/-0
	R	φ13±0.2	φ13±0.2
	S	φ21±0.8	φ21±0.8
	U	2.0±0.5	2.0±0.5
	W	9±1	9±1
Qty	3000/1000	3000/1000	



	KSX-23	CX-4025S	KSX-35 CX-96F	CX-53F CX-53G	CX-8045G CX-17F	KSX-36	CX-49F	CX-5FW CX-5FD	CX-49L	
T A P E	A	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	
	B	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	
	C	φ1.5±0.1/-0	φ1.55±0.05	φ1.5±0.1	φ1.55±0.1	φ1.5±0.1	φ1.5±0.1	φ1.55±0.05	φ1.55±0.05	φ1.5±0.1
	D	4.0±0.1	4.0±0.1	8.0±0.1	8.0±0.1	8.0±0.1	8.0±0.1	8.0±0.1	12.0±0.1	16.0±0.1
	E	5.5±0.1	5.5±0.1	5.5±0.1	5.5±0.1	7.5±0.1	7.5±0.1	11.5±0.1	11.5±0.1	11.5±0.1
	F	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1
	G	12.0±0.3	12.0±0.3	12.0±0.3	12.0±0.2	16.0±0.3	16.0±0.3	24.0±0.3	24.0±0.3	24.0±0.3
	H	φ1.5±0.1/-0	φ1.05±0.1	φ1.5±0.1	φ1.55±0.1	φ1.55±0.05	φ1.6±0.1	φ2.05±0.05	φ2.05±0.05	φ2.2±0.1
	J	3.5±0.1	4.2±0.1	5.5±0.1	5.4±0.1	8.4±0.1	6.5±0.1	11.5±0.1	12.2±0.1	—
	L	2.8±0.1	2.7±0.1	3.7±0.1	3.6±0.1	4.9±0.1	4.2±0.1	5.4±0.1	5.85±0.1	—
	N	1.0±0.1	0.95±0.05	1.4±0.1	1.7±0.1	2.1±0.1	1.5±0.1	5.5±0.1	2.8±0.1	6.5±0.1
O	0.3±0.05	0.2±0.05	0.3±0.05	0.25±0.05	0.3±0.05	0.2±0.05	0.3±0.05	0.3±0.05	0.5±0.05	
R E E L	P	φ330±2	φ180+0/-3	φ330±2/φ178±2	φ330±2/φ254±2	φ330±2/φ254±2	φ330±2/φ178±2	φ330±2	φ330±2	φ330±2
	Q	φ100±1	φ60+1/-0	φ80±2/φ100±1	φ100±1	φ80±1	φ80±2	φ100±1	φ100±1	φ100±1
	R	φ13±0.2	φ13±0.2	φ13±0.2	φ13±0.2	φ13±0.2	φ13±0.2	φ13±0.5	φ13±0.5	φ13±0.5
	S	φ21±0.8	φ21±0.8	φ21±0.8	φ21±0.8	φ21±0.8	φ21±0.8	φ21±0.5	φ21±0.5	—
	U	2.0±0.5	2.0±0.5	2.0±0.5	2.0±0.5	2.0±0.5	2.0±0.5	2.0±0.2	2.0±0.5	—
	W	13.5±0.5	13±1	13.5+1/-0.5	13.4+2/-0	16.0+2/-0	17.5+2/-0	25.5±0.5	24.4+2/-0	25.5+1/-0.5
Qty	5000/3000	3000/1000	5000/1000	3000/1000	3000/1000	5000/1000	1000	1000	5000	

**ORDERING FORMAT FOR CRYSTAL UNITS**

Please specify the following items when ordering crystal units.

1. Type \_\_\_\_\_
2. Nominal Frequency \_\_\_\_\_ Hz
3. Overtone order \_\_\_\_\_
4. Frequency Tolerance \_\_\_\_\_  $\times 10^{-6}$  MAX. (at 25°C)
5. Frequency Stability vs. Temperature Range (referred to 25°C)  
 \_\_\_\_\_  $\times 10^{-6}$  MAX, \_\_\_\_\_ °C ~ \_\_\_\_\_ °C
6. Motional Resistance \_\_\_\_\_  $\Omega$  MAX.
7. Load Capacitance( $C_L$ ) \_\_\_\_\_ pF
8. Drive Level \_\_\_\_\_ mW
9. Shunt Capacitance( $C_0$ ) \_\_\_\_\_ pF Max.
10. Others \_\_\_\_\_
11. Marking \_\_\_\_\_
12. Application \_\_\_\_\_